ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	PC. Bannockl	burn. Illinois. A	ll rights reserved untions.	under both	This docum level parts, t	ent is a declara he declaration	tion of the s encompasse	ubstances es all lowe	within the r level mat	manufacture erials for wh	er listed iten hich the ma	n. Note: nufacture	if the item is an as r has engineering	sembly with lowe responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form T http://www.ipc.org/IPC-175x Distrib				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Material					ls and Mfg Information				
Supplier Information															
Company name*			Company unique ID			Unique ID Authority					Response Date*				
nsemi												2024-05-17			
ntact Name Title - Contact			t			Phone - Contact*				Email - Contact*					
Product-Env-Stewards Product E			Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Rep			resentative			Phone - Representative*				Email - Representative*					
Product-Env-Stewards Product En			wiro Compliance			NA				Product-Env-Stewards@onsemi.com					
Requester Item Number	er Mfr Item Nu		Number Mfr Item Name			Effective Dat	e Version	.]	Manufacturing Site		W	eight*	UOM	Unit Type	
	SURA82	260T3G-VF01	REC SMA 2A 600V ULTFST TR		R	2024-05-17			VN5		76	.66	mg	Each	
Manufacturing Proccess Informa	tion		•					<u>,</u>					·		
Terminal Plating / Grid Array M	al Plating / Grid Array Material Terminal Base .		Alloy	J-STD-020 MSL Rating		Peak Pro	Peak Process Body Temperatu		ure Max Time at Peak Temper		Temperatur	e Num	ber of Reflow Cyc	cles	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30		seconds	3			
Comments															
evel 1 - maximum time at peak temperat	ire during so	ldering is 10-3	0 seconds												
or more information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	7.0	mg	Supplier	Zinc (Zn)	7440-66-6		0.0084	mg
			Supplier	Iron (Fe)	7439-89-6		0.1645	mg
			Supplier	Copper (Cu)	7440-50-8		6.825	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0021	mg
Die	1.12	mg	Supplier	Silicon (Si)	7440-21-3		1.12	mg
Die Attach Solder	3.45	mg	Supplier	Silver (Ag)	7440-22-4		0.0862	mg
			А	Lead (Pb)	7439-92-1	7a	3.1913	mg
			Supplier	Tin (Sn)	7440-31-5		0.1725	mg
Lead Frame	28.84	mg	Supplier	Zinc (Zn)	7440-66-6		0.0346	mg
			Supplier	Iron (Fe)	7439-89-6		0.6922	mg
			Supplier	Copper (Cu)	7440-50-8		28.0902	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0231	mg
Mold Compound-Black	34.87	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		3.487	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1743	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		5.0561	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		22.6655	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.487	mg
Plating	1.38	mg	Supplier	Tin (Sn)	7440-31-5		1.38	mg